What is "**Embedded - Microcontrollers**"?

"**Embedded - Microcontrollers**" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "**Embedded - Microcontrollers**"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	35
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512gp204t-e-pt

TABLE 4-9:   INPUT CAPTURE 1 THROUGH INPUT CAPTURE 4 REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IC1CON1	0140	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
IC1CON2	0142	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					000D
IC1BUF	0144	Input Capture 1 Buffer Register																xxxx
IC1TMR	0146	Input Capture 1 Timer																0000
IC2CON1	0148	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
IC2CON2	014A	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					000D
IC2BUF	014C	Input Capture 2 Buffer Register																xxxx
IC2TMR	014E	Input Capture 2 Timer																0000
IC3CON1	0150	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
IC3CON2	0152	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					000D
IC3BUF	0154	Input Capture 3 Buffer Register																xxxx
IC3TMR	0156	Input Capture 3 Timer																0000
IC4CON1	0158	—	—	ICSIDL	ICTSEL<2:0>			—	—	—	ICI<1:0>		ICOV	ICBNE	ICM<2:0>			0000
IC4CON2	015A	—	—	—	—	—	—	—	IC32	ICTRIG	TRIGSTAT	—	SYNCSEL<4:0>					000D
IC4BUF	015C	Input Capture 4 Buffer Register																xxxx
IC4TMR	015E	Input Capture 4 Timer																0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 8-2: DMAxREQ: DMA CHANNEL x IRQ SELECT REGISTER

R/S-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
FORCE[1]	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IRQSEL7	IRQSEL6	IRQSEL5	IRQSEL4	IRQSEL3	IRQSEL2	IRQSEL1	IRQSEL0
bit 7							bit 0

Legend:			
	S = Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **FORCE:** Force DMA Transfer bit[1]

1 = Forces a single DMA transfer (Manual mode)
0 = Automatic DMA transfer initiation by DMA request

bit 14-8 **Unimplemented:** Read as '0'

bit 7-0 **IRQSEL<7:0>:** DMA Peripheral IRQ Number Select bits

01000110 = ECAN1 – TX Data Request[2]
00100110 = IC4 – Input Capture 4
00100101 = IC3 – Input Capture 3
00100010 = ECAN1 – RX Data Ready[2]
00100001 = SPI2 Transfer Done
00011111 = UART2TX – UART2 Transmitter
00011110 = UART2RX – UART2 Receiver
00011100 = TMR5 – Timer5
00011011 = TMR4 – Timer4
00011010 = OC4 – Output Compare 4
00011001 = OC3 – Output Compare 3
00001101 = ADC1 – ADC1 Convert done
00001100 = UART1TX – UART1 Transmitter
00001011 = UART1RX – UART1 Receiver
00001010 = SPI1 – Transfer Done
00001000 = TMR3 – Timer3
00000111 = TMR2 – Timer2
00000110 = OC2 – Output Compare 2
00000101 = IC2 – Input Capture 2
00000010 = OC1 – Output Compare 1
00000001 = IC1 – Input Capture 1
00000000 = INT0 – External Interrupt 0

Note 1: The FORCE bit cannot be cleared by user software. The FORCE bit is cleared by hardware when the forced DMA transfer is complete or the channel is disabled (CHEN = 0).

2: This selection is available in dsPIC33EPXXXGP/MC50X devices only.

REGISTER 10-2: PMD2: PERIPHERAL MODULE DISABLE CONTROL REGISTER 2

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11 **IC4MD:** Input Capture 4 Module Disable bit

1 = Input Capture 4 module is disabled
0 = Input Capture 4 module is enabled

bit 10 **IC3MD:** Input Capture 3 Module Disable bit

1 = Input Capture 3 module is disabled
0 = Input Capture 3 module is enabled

bit 9 **IC2MD:** Input Capture 2 Module Disable bit

1 = Input Capture 2 module is disabled
0 = Input Capture 2 module is enabled

bit 8 **IC1MD:** Input Capture 1 Module Disable bit

1 = Input Capture 1 module is disabled
0 = Input Capture 1 module is enabled

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **OC4MD:** Output Compare 4 Module Disable bit

1 = Output Compare 4 module is disabled
0 = Output Compare 4 module is enabled

bit 2 **OC3MD:** Output Compare 3 Module Disable bit

1 = Output Compare 3 module is disabled
0 = Output Compare 3 module is enabled

bit 1 **OC2MD:** Output Compare 2 Module Disable bit

1 = Output Compare 2 module is disabled
0 = Output Compare 2 module is enabled

bit 0 **OC1MD:** Output Compare 1 Module Disable bit

1 = Output Compare 1 module is disabled
0 = Output Compare 1 module is enabled

11.1.1 OPEN-DRAIN CONFIGURATION

In addition to the PORTx, LATx and TRISx registers for data control, port pins can also be individually configured for either digital or open-drain output. This is controlled by the Open-Drain Control register, ODCx, associated with each port. Setting any of the bits configures the corresponding pin to act as an open-drain output.

The open-drain feature allows the generation of outputs other than V$_{DD}$ by using external pull-up resistors. The maximum open-drain voltage allowed on any pin is the same as the maximum V$_{IH}$ specification for that particular pin.

See the **"Pin Diagrams"** section for the available 5V tolerant pins and Table 30-11 for the maximum V$_{IH}$ specification for each pin.

11.2 Configuring Analog and Digital Port Pins

The ANSELx register controls the operation of the analog port pins. The port pins that are to function as analog inputs or outputs must have their corresponding ANSELx and TRISx bits set. In order to use port pins for I/O functionality with digital modules, such as Timers, UARTs, etc., the corresponding ANSELx bit must be cleared.

The ANSELx register has a default value of 0xFFFF; therefore, all pins that share analog functions are analog (not digital) by default.

Pins with analog functions affected by the ANSELx registers are listed with a buffer type of analog in the Pinout I/O Descriptions (see Table 1-1).

If the TRISx bit is cleared (output) while the ANSELx bit is set, the digital output level (V$_{OH}$ or V$_{OL}$) is converted by an analog peripheral, such as the ADC module or comparator module.

When the PORTx register is read, all pins configured as analog input channels are read as cleared (a low level).

Pins configured as digital inputs do not convert an analog input. Analog levels on any pin defined as a digital input (including the ANx pins) can cause the input buffer to consume current that exceeds the device specifications.

11.2.1 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically this instruction would be a NOP, as shown in Example 11-1.

11.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature can detect input Change-of-States even in Sleep mode, when the clocks are disabled. Every I/O port pin can be selected (enabled) for generating an interrupt request on a Change-of-State.

Three control registers are associated with the Change Notification (CN) functionality of each I/O port. The CNENx registers contain the CN interrupt enable control bits for each of the input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each I/O pin also has a weak pull-up and a weak pull-down connected to it. The pull-ups and pull-downs act as a current source or sink source connected to the pin and eliminate the need for external resistors when push button, or keypad devices are connected. The pull-ups and pull-downs are enabled separately, using the CNPUx and the CNPDx registers, which contain the control bits for each of the pins. Setting any of the control bits enables the weak pull-ups and/or pull-downs for the corresponding pins.

Note:	Pull-ups and pull-downs on Change Notification pins should always be disabled when the port pin is configured as a digital output.

EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV    0xFF00, W0   ; Configure PORTB<15:8>
                    ; as inputs
MOV    W0, TRISB    ; and PORTB<7:0>
                    ; as outputs
NOP                 ; Delay 1 cycle
BTSS   PORTB, #13   ; Next Instruction
```

11.4.4.2 Output Mapping

In contrast to inputs, the outputs of the Peripheral Pin Select options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPORx registers are used to control output mapping. Like the RPINRx registers, each register contains sets of 6-bit fields, with each set associated with one RPn pin (see Register 11-18 through Register 11-27). The value of the bit field corresponds to one of the peripherals and that peripheral's output is mapped to the pin (see Table 11-3 and Figure 11-3).

A null output is associated with the output register Reset value of '0'. This is done to ensure that remappable outputs remain disconnected from all output pins by default.

FIGURE 11-3: MULTIPLEXING REMAPPABLE OUTPUT FOR RPn
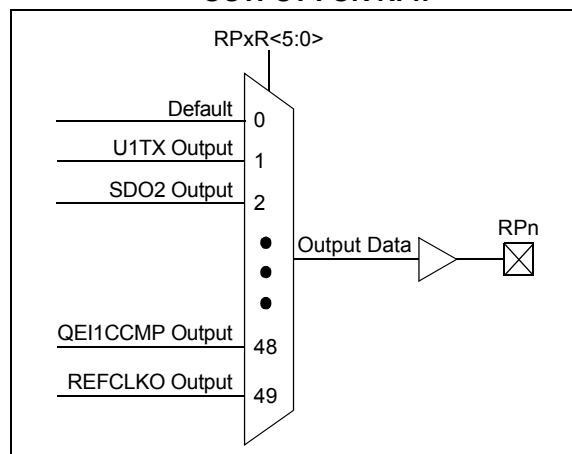
11.4.4.3 Mapping Limitations

The control schema of the peripheral select pins is not limited to a small range of fixed peripheral configurations. There are no mutual or hardware-enforced lockouts between any of the peripheral mapping SFRs. Literally any combination of peripheral mappings across any or all of the RPn pins is possible. This includes both many-to-one and one-to-many mappings of peripheral inputs and outputs to pins. While such mappings may be technically possible from a configuration point of view, they may not be supportable from an electrical point of view.

TABLE 11-3: OUTPUT SELECTION FOR REMAPPABLE PINS (RPn)

Function	RPxR<5:0>	Output Name
Default PORT	000000	RPn tied to Default Pin
U1TX	000001	RPn tied to UART1 Transmit
U2TX	000011	RPn tied to UART2 Transmit
SDO2	001000	RPn tied to SPI2 Data Output
SCK2	001001	RPn tied to SPI2 Clock Output
$\overline{\text{SS2}}$	001010	RPn tied to SPI2 Slave Select
C1TX[2]	001110	RPn tied to CAN1 Transmit
OC1	010000	RPn tied to Output Compare 1 Output
OC2	010001	RPn tied to Output Compare 2 Output
OC3	010010	RPn tied to Output Compare 3 Output
OC4	010011	RPn tied to Output Compare 4 Output
C1OUT	011000	RPn tied to Comparator Output 1
C2OUT	011001	RPn tied to Comparator Output 2
C3OUT	011010	RPn tied to Comparator Output 3
SYNCO1[1]	101101	RPn tied to PWM Primary Time Base Sync Output
QEI1CCMP[1]	101111	RPn tied to QEI 1 Counter Comparator Output
REFCLKO	110001	RPn tied to Reference Clock Output
C4OUT	110010	RPn tied to Comparator Output 4

Note 1: This function is available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: This function is available in dsPIC33EPXXXGP/MC50X devices only.

REGISTER 14-2: ICxCON2: INPUT CAPTURE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Input Source Select for Synchronization and Trigger Operation bits[4]

11111 = No Sync or Trigger source for ICx
11110 = Reserved
11101 = Reserved
11100 = CTMU module synchronizes or triggers ICx
11011 = ADC1 module synchronizes or triggers ICx[5]
11010 = CMP3 module synchronizes or triggers ICx[5]
11001 = CMP2 module synchronizes or triggers ICx[5]
11000 = CMP1 module synchronizes or triggers ICx[5]
10111 = Reserved
10110 = Reserved
10101 = Reserved
10100 = Reserved
10011 = IC4 module synchronizes or triggers ICx
10010 = IC3 module synchronizes or triggers ICx
10001 = IC2 module synchronizes or triggers ICx
10000 = IC1 module synchronizes or triggers ICx
01111 = Timer5 synchronizes or triggers ICx
01110 = Timer4 synchronizes or triggers ICx
01101 = Timer3 synchronizes or triggers ICx **(default)**
01100 = Timer2 synchronizes or triggers ICx
01011 = Timer1 synchronizes or triggers ICx
01010 = PTGOx module synchronizes or triggers ICx[6]
01001 = Reserved
01000 = Reserved
00111 = Reserved
00110 = Reserved
00101 = Reserved
00100 = OC4 module synchronizes or triggers ICx
00011 = OC3 module synchronizes or triggers ICx
00010 = OC2 module synchronizes or triggers ICx
00001 = OC1 module synchronizes or triggers ICx
00000 = No Sync or Trigger source for ICx

Note 1: The IC32 bit in both the Odd and Even IC must be set to enable Cascade mode.

2: The input source is selected by the SYNCSEL<4:0> bits of the ICxCON2 register.

3: This bit is set by the selected input source (selected by SYNCSEL<4:0> bits). It can be read, set and cleared in software.

4: Do not use the ICx module as its own Sync or Trigger source.

5: This option should only be selected as a trigger source and not as a synchronization source.

6: Each Input Capture x (ICx) module has one PTG input source. See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for more information.
PTGO8 = IC1
PTGO9 = IC2
PTGO10 = IC3
PTGO11 = IC4

16.1.2 WRITE-PROTECTED REGISTERS

On dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices, write protection is implemented for the IOCONx and FCLCONx registers. The write protection feature prevents any inadvertent writes to these registers. This protection feature can be controlled by the PWMLOCK Configuration bit (FOSCSEL<6>). The default state of the write protection feature is enabled (PWMLOCK = 1). The write protection feature can be disabled by configuring, PWMLOCK = 0.

To gain write access to these locked registers, the user application must write two consecutive values of (0xABCD and 0x4321) to the PWMKEY register to perform the unlock operation. The write access to the IOCONx or FCLCONx registers must be the next SFR access following the unlock process. There can be no other SFR accesses during the unlock process and subsequent write access. To write to both the IOCONx and FCLCONx registers requires two unlock operations.

The correct unlocking sequence is described in Example 16-1.

EXAMPLE 16-1:   PWMx WRITE-PROTECTED REGISTER UNLOCK SEQUENCE

```
; FLT32 pin must be pulled low externally in order to clear and disable the fault
; Writing to FCLCON1 register requires unlock sequence

mov #0xabcd,w10        ; Load first unlock key to w10 register
mov #0x4321,w11        ; Load second unlock key to w11 register
mov #0x0000,w0         ; Load desired value of FCLCON1 register in w0
mov w10, PWMKEY        ; Write first unlock key to PWMKEY register
mov w11, PWMKEY        ; Write second unlock key to PWMKEY register
mov w0,FCLCON1         ; Write desired value to FCLCON1 register


; Set PWM ownership and polarity using the IOCON1 register
; Writing to IOCON1 register requires unlock sequence

mov #0xabcd,w10        ; Load first unlock key to w10 register
mov #0x4321,w11        ; Load second unlock key to w11 register
mov #0xF000,w0         ; Load desired value of IOCON1 register in w0
mov w10, PWMKEY        ; Write first unlock key to PWMKEY register
mov w11, PWMKEY        ; Write second unlock key to PWMKEY register
mov w0,IOCON1          ; Write desired value to IOCON1 register
```

REGISTER 16-13: IOCONx: PWMx I/O CONTROL REGISTER[2] (CONTINUED)

bit 1   **SWAP:** SWAP PWMxH and PWMxL Pins bit

               1 = PWMxH output signal is connected to PWMxL pins; PWMxL output signal is connected to PWMxH pins

               0 = PWMxH and PWMxL pins are mapped to their respective pins

bit 0   **OSYNC:** Output Override Synchronization bit

               1 = Output overrides via the OVRDAT<1:0> bits are synchronized to the PWMx period boundary

               0 = Output overrides via the OVDDAT<1:0> bits occur on the next CPU clock boundary

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = 1).

      2: If the PWMLOCK Configuration bit (FOSCSEL<6>) is a '1', the IOCONx register can only be written after the unlock sequence has been executed.

REGISTER 17-13: QEI1LECH: QEI1 LESS THAN OR EQUAL COMPARE HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			QEILEC<31:24>				
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			QEILEC<23:16>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0   **QEILEC<31:16>:** High Word Used to Form 32-Bit Less Than or Equal Compare Register (QEI1LEC) bits

REGISTER 17-14: QEI1LECL: QEI1 LESS THAN OR EQUAL COMPARE LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			QEILEC<15:8>				
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
			QEILEC<7:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0   **QEILEC<15:0>:** Low Word Used to Form 32-Bit Less Than or Equal Compare Register (QEI1LEC) bits

24.2 PTG Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

> **Note:** In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

24.2.1 KEY RESOURCES

- **"Peripheral Trigger Generator"** (DS70669) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

TABLE 30-9: **DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔIWDT)[1]**

DC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended	
Parameter No.	Typ.	Max.	Units	Conditions	
DC61d	8	—	μA	-40°C	
DC61a	10	—	μA	+25°C	3.3V
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔIWDT current is the additional current consumed when the module is enabled. This current should be added to the base IPD current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS					Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	Typ.	Max.	Doze Ratio	Units	Conditions		
Doze Current (IDOZE)[1]							
DC73a[2]	35	—	1:2	mA	-40°C	3.3V	FOSC = 140 MHz
DC73g	20	30	1:128	mA			
DC70a[2]	35	—	1:2	mA	+25°C	3.3V	FOSC = 140 MHz
DC70g	20	30	1:128	mA			
DC71a[2]	35	—	1:2	mA	+85°C	3.3V	FOSC = 140 MHz
DC71g	20	30	1:128	mA			
DC72a[2]	28	—	1:2	mA	+125°C	3.3V	FOSC = 120 MHz
DC72g	15	30	1:128	mA			

Note 1: IDOZE is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDOZE measurements are as follows:
- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DI60a	IICL	**Input Low Injection Current**	0	—	-5[4,7]	mA	All pins except V_{DD}, V_{SS}, AV_{DD}, AV_{SS}, $\overline{MCLR}$, V_{CAP} and RB7
DI60b	IICH	**Input High Injection Current**	0	—	+5[5,6,7]	mA	All pins except V_{DD}, V_{SS}, AV_{DD}, AV_{SS}, $\overline{MCLR}$, V_{CAP}, RB7 and all 5V tolerant pins[6]
DI60c	ΣIICT	**Total Input Injection Current (sum of all I/O and control pins)**	-20[8]	—	+20[8]	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins ($\mid$ IICL + $\mid$ IICH $\mid$) ≤ ΣIICT

Note 1: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

   2: Negative current is defined as current sourced by the pin.

   3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

   4: V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.

   5: Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.

   6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

   7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

   8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-9: **HIGH-SPEED PWMx MODULE FAULT TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)**
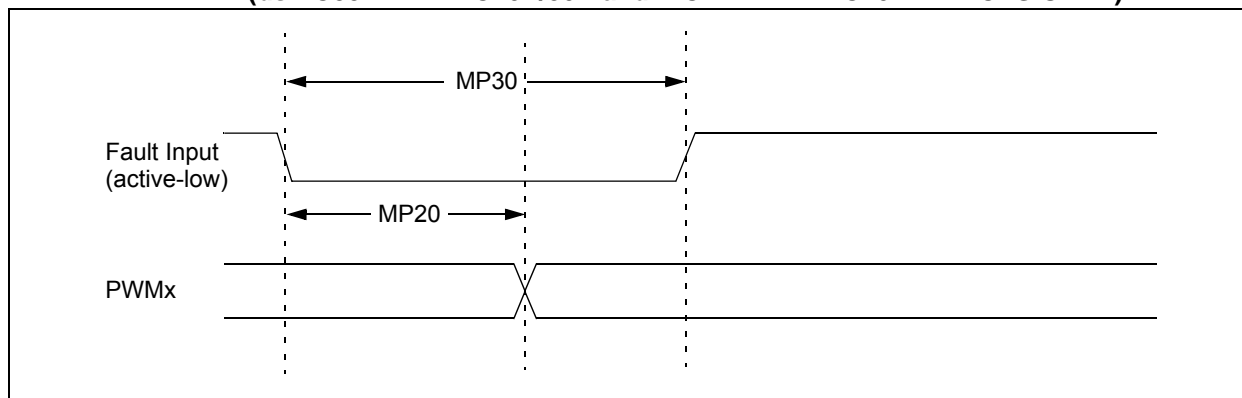

FIGURE 30-10: **HIGH-SPEED PWMx MODULE TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)**
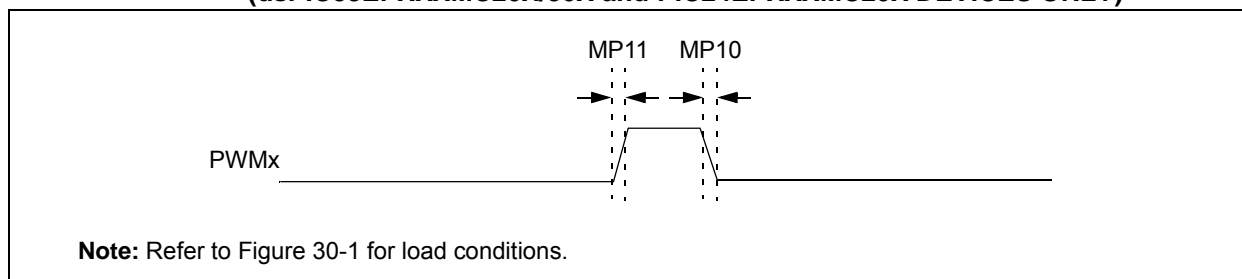

Note: Refer to Figure 30-1 for load conditions.

TABLE 30-29: **HIGH-SPEED PWMx MODULE TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)**

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic[1]	Min.	Typ.	Max.	Units	Conditions
MP10	T$_{FPWM}$	PWMx Output Fall Time	—	—	—	ns	See Parameter DO32
MP11	T$_{RPWM}$	PWMx Output Rise Time	—	—	—	ns	See Parameter DO31
MP20	T$_{FD}$	Fault Input ↓ to PWMx I/O Change	—	—	15	ns	
MP30	T$_{FH}$	Fault Input Pulse Width	15	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

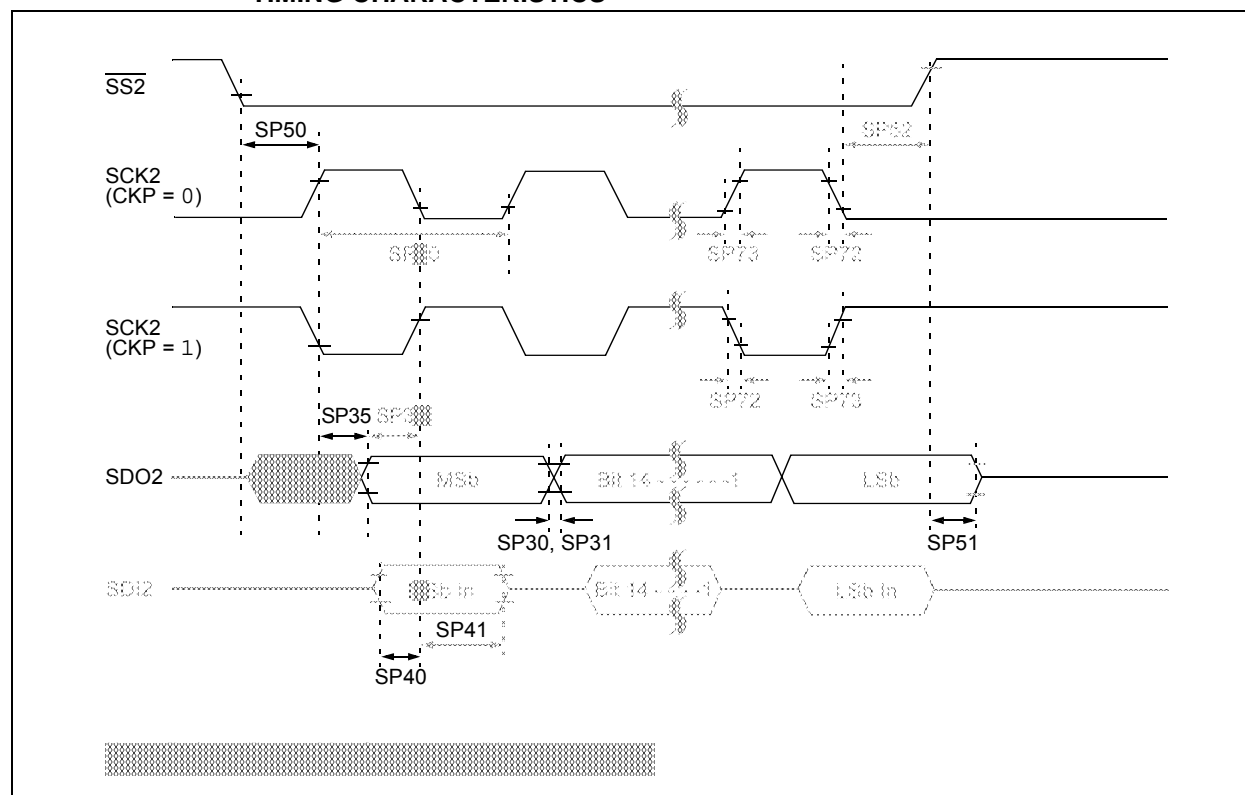**FIGURE 30-20:** **SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0)**
TIMING CHARACTERISTICS

TABLE 30-50: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param. No.	Symbol	Characteristic[3]		Min.	Max.	Units	Conditions
IS10	$T_{LO:SCL}$	Clock Low Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	1.3	—	µs	
			1 MHz mode[1]	0.5	—	µs	
IS11	$T_{HI:SCL}$	Clock High Time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			1 MHz mode[1]	0.5	—	µs	
IS20	$T_{F:SCL}$	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode[1]	—	100	ns	
IS21	$T_{R:SCL}$	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode[1]	—	300	ns	
IS25	$T_{SU:DAT}$	Data Input Setup Time	100 kHz mode	250	—	ns	
			400 kHz mode	100	—	ns	
			1 MHz mode[1]	100	—	ns	
IS26	$T_{HD:DAT}$	Data Input Hold Time	100 kHz mode	0	—	µs	
			400 kHz mode	0	0.9	µs	
			1 MHz mode[1]	0	0.3	µs	
IS30	$T_{SU:STA}$	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
			1 MHz mode[1]	0.25	—	µs	
IS31	$T_{HD:STA}$	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
			1 MHz mode[1]	0.25	—	µs	
IS33	$T_{SU:STO}$	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
			1 MHz mode[1]	0.6	—	µs	
IS34	$T_{HD:STO}$	Stop Condition Hold Time	100 kHz mode	4	—	µs	
			400 kHz mode	0.6	—	µs	
			1 MHz mode[1]	0.25		µs	
IS40	$T_{AA:SCL}$	Output Valid From Clock	100 kHz mode	0	3500	ns	
			400 kHz mode	0	1000	ns	
			1 MHz mode[1]	0	350	ns	
IS45	$T_{BF:SDA}$	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode[1]	0.5	—	µs	
IS50	CB	Bus Capacitive Loading		—	400	pF	
IS51	T_{PGD}	Pulse Gobbler Delay		65	390	ns	(Note 2)

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).
   2: Typical value for this parameter is 130 ns.
   3: These parameters are characterized, but not tested in manufacturing.

TABLE 30-58: ADC MODULE SPECIFICATIONS (12-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)[1] Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
ADC Accuracy (12-Bit Mode)							
AD20a	Nr	Resolution	\multicolumn{2}{c}{12 Data Bits}		bits	
AD21a	INL	Integral Nonlinearity	-2.5	—	2.5	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-5.5	—	5.5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD22a	DNL	Differential Nonlinearity	-1	—	1	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-1	—	1	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD23a	GERR	Gain Error[3]	-10	—	10	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-10	—	10	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD24a	EOFF	Offset Error	-5	—	5	LSb	-40°C ≤ TA ≤ +85°C **(Note 2)**
			-5	—	5	LSb	+85°C < TA ≤ +125°C **(Note 2)**
AD25a	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance (12-Bit Mode)							
AD30a	THD	Total Harmonic Distortion[3]	—	75	—	dB	
AD31a	SINAD	Signal to Noise and Distortion[3]	—	68	—	dB	
AD32a	SFDR	Spurious Free Dynamic Range[3]	—	80	—	dB	
AD33a	FNYQ	Input Signal Bandwidth[3]	—	250	—	kHz	
AD34a	ENOB	Effective Number of Bits[3]	11.09	11.3	—	bits	

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: For all accuracy specifications, VINL = AVSS = VREFL = 0V and AVDD = VREFH = 3.6V.

3: Parameters are characterized but not tested in manufacturing.

FIGURE 30-37: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = `01`, SIMSAM = `0`, ASAM = `0`, SSRC<2:0> = `000`, SSRCG = `0`)
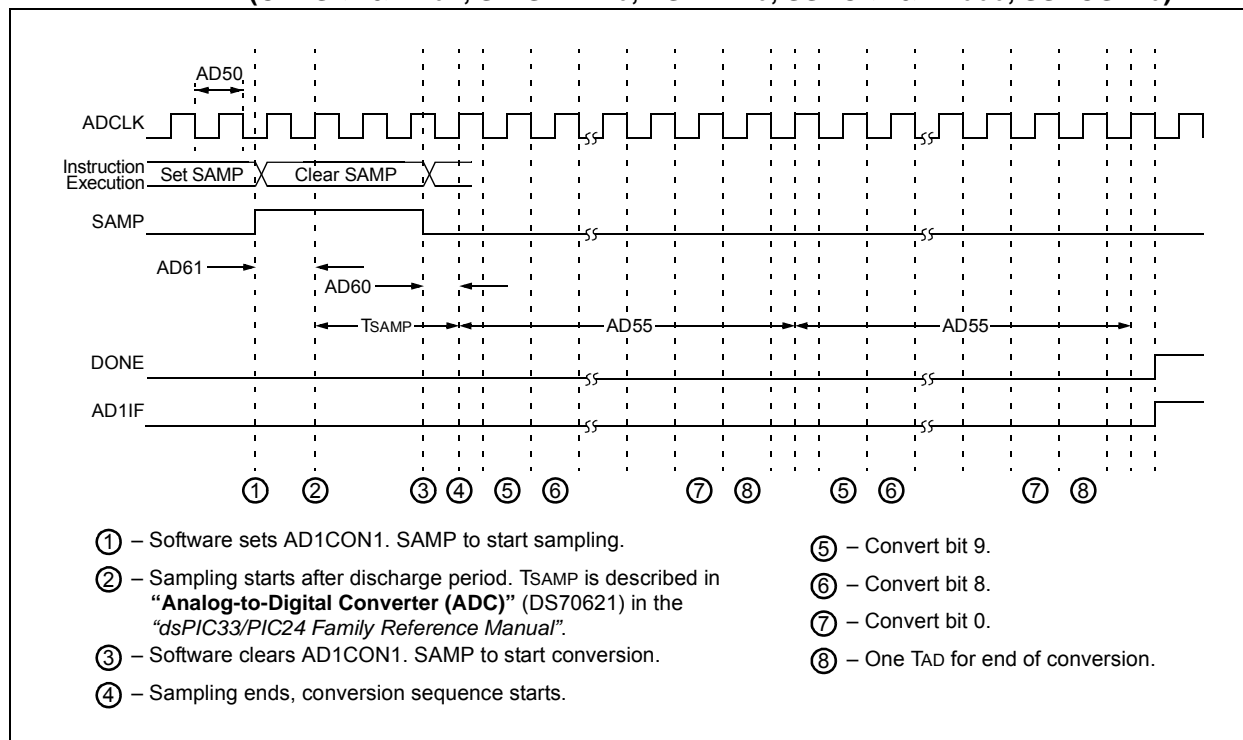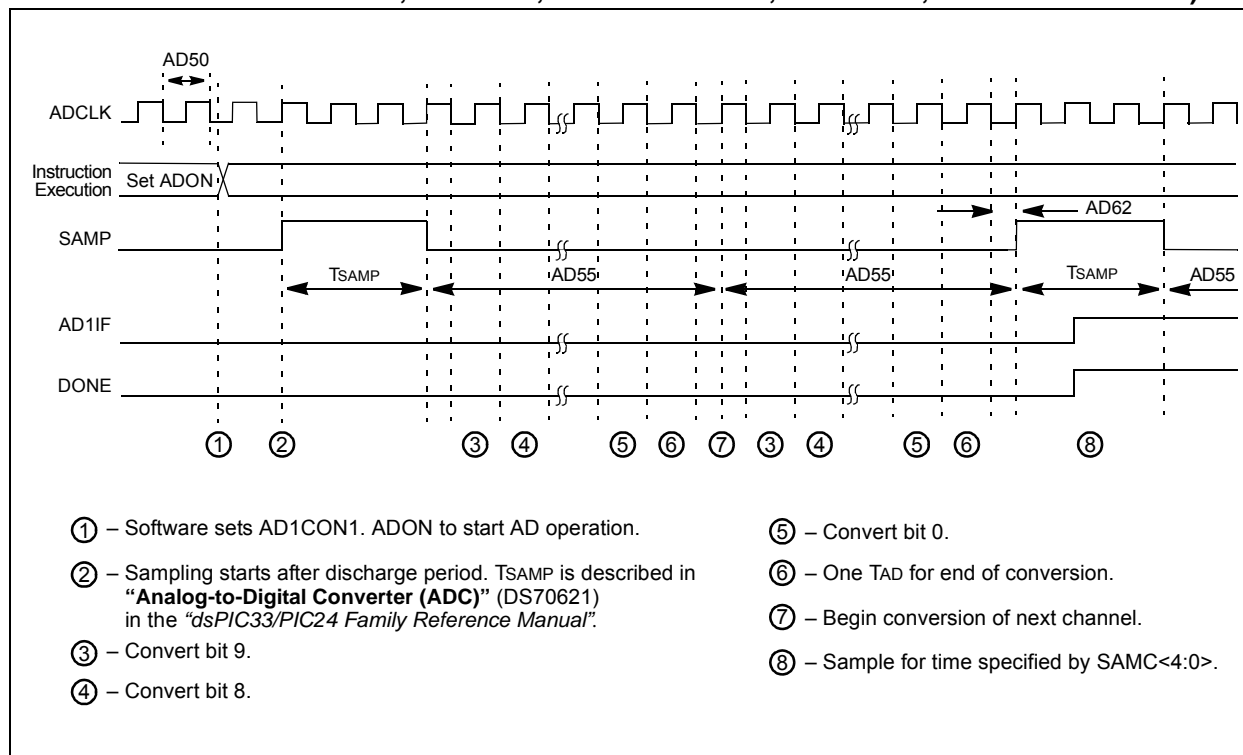

① – Software sets AD1CON1. SAMP to start sampling.

② – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) in the *"dsPIC33/PIC24 Family Reference Manual"*.

③ – Software clears AD1CON1. SAMP to start conversion.

④ – Sampling ends, conversion sequence starts.

⑤ – Convert bit 9.

⑥ – Convert bit 8.

⑦ – Convert bit 0.

⑧ – One TAD for end of conversion.

FIGURE 30-38: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = `01`, SIMSAM = `0`, ASAM = `1`, SSRC<2:0> = `111`, SSRCG = `0`, SAMC<4:0> = `00010`)

① – Software sets AD1CON1. ADON to start AD operation.

② – Sampling starts after discharge period. TSAMP is described in **"Analog-to-Digital Converter (ADC)"** (DS70621) in the *"dsPIC33/PIC24 Family Reference Manual"*.

③ – Convert bit 9.

④ – Convert bit 8.

⑤ – Convert bit 0.

⑥ – One TAD for end of conversion.

⑦ – Begin conversion of next channel.

⑧ – Sample for time specified by SAMC<4:0>.

NOTES:

48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging
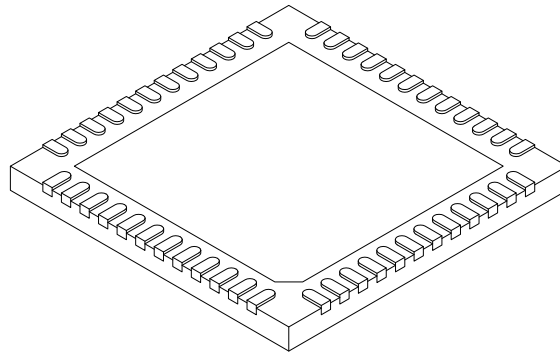
	Units		MILLIMETERS	
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		48	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.45	4.60	4.75
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.45	4.60	4.75
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-153A Sheet 2 of 2

NOTES: